IPC ASSOCIATION CONF	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both le	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute								als and Mf	g Informati	on		
upplier Inf	formation													
Company name*			Company unique ID			U	Unique ID Authority				Response Date*			
nsemi											2025-05-18			
Contact Name		Title - Contact			P	Phone - Contact*				Email - Contact*				
Product-Env-S	Stewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
uthorized Re	epresentative*	Title - Representative			P	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Req	quester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	e Version Manufacturing Site		V	/eight*	UOM	Unit Type	
		S2B SR S		SR SMB GPPN 1.5A 100V			2025-05-18		T	TSCBE		0.0004	mg	Each
	ring Process Informa		Comminal Description	Aller	STD 020 MSL I	Datina	Dook Dee	and Dody To		May Time at Prol-	Tommon	ma Nauer-le	on of Boflow Co	Jac
2 ,		,		STD-020 MSL I	Kating	Peak Process Body Temper		•				er of Reflow Cyc	eies	
•	tte Tin (Sn) - annealed	(CU Alloy	1			260		C	30	second	s 3		
omments			11. 1. 1. 10.1	10										
	num time at peak temperat													
r more infor	rmation regarding materia	1 composition	piease refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itaaliaty and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In											
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead). Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature R		,									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	10.667	mg	Supplier	Copper (Cu)	7440-50-8		10.667	mg
Die	1.2132	mg	Supplier	Silicon (Si)	7440-21-3		1.0919	mg
			В	Nickel (Ni)	7440-02-0		0.0079	mg
			Supplier	Gold (Au)	7440-57-5		0.0018	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.1116	mg
Die Attach Solder	2.3616	mg	Supplier	Silver (Ag)	7440-22-4		0.059	mg
			A	Lead (Pb)	7439-92-1	7a	2.1845	mg
			Supplier	Tin (Sn)	7440-31-5		0.1181	mg
Lead Frame	26.802	mg	Supplier	Iron (Fe)	7439-89-6		0.0322	mg
			Supplier	Copper (Cu)	7440-50-8		26.7618	mg
			Supplier	Phosphorus (P)	7723-14-0		0.008	mg
Mold Compound-Black	48.755	mg		Metal Hydroxide	proprietary data		1.7064	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		3.9004	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2438	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		39.004	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		3.9004	mg
Plating	0.2016	mg	Supplier	Tin (Sn)	7440-31-5		0.2016	mg